



## Product Change Notification / ASER-18BMYN527

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**Date:**

20-Oct-2020

**Product Category:**

Memory

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4218 Final Notice: Qualification of MMT as a new assembly site for selected SST39xxx products available in 32L PLCC (11.5x14x3.37mm) package.

**Affected CPNs:**

[ASER-18BMYN527\\_Affected\\_CPN\\_10202020.pdf](#)  
[ASER-18BMYN527\\_Affected\\_CPN\\_10202020.csv](#)

**Notification Text:**

**PCN Status:** Final notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of MMT as a new assembly site for selected SST39xxx products available in 32L PLCC (11.5x14x3.37mm) package.

**Pre Change:**

Assembled at LPI or GTK assembly site using 8340 die attach and C151 lead frame material.

**Post Change:** Assembled at MMT using 3280 die attach and A194 lead frame material.

**Pre and Post Change Summary:**

		Pre Change		Post Change
Assembly Site		Lingsen Precision Industries, LTD. (LPI)	Greatek Electronic Inc. (GTK)	Microchip Technology Thailand (MMT)
Wire material		Au	Au	Au
Die attach material		8340	8340	3280
Molding compound material		G600	G600	G600
Lead frame material		C151	C151	A194

**Impacts to Data Sheet:** None

**Change Impact:** None

**Reason for Change:** Due to unforeseen business conditions, MMT has been qualified as a new assembly effective immediately.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** September 20, 2020 (date code: 2039)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

### Time Table Summary:

	April 2020					-->	September 2020				
	1 4	1 5	1 6	1 7	1 8		3 6	3 7	3 8	3 9	4 0
Initial PCN Issue Date				X							
Final PCN Issue Date									X		
Qual Report Availability										X	
Estimated First Ship Date										X	

**Method to Identify Change:** Traceability code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_{#}\_Qual\_Report.

**Revision History:** April 21, 2020: Issued initial notification. September 18, 2020: Issued final notification. October 20, 2020: Re-issued the final notification to include the Qualification Report. Corrected pre and post change to correct the word bond wire to die attach material.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_ASER-18BMYN527\\_Qual\\_Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

## **Terms and Conditions:**

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If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.